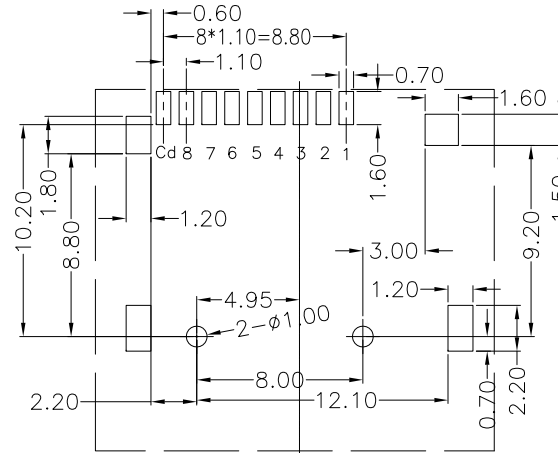
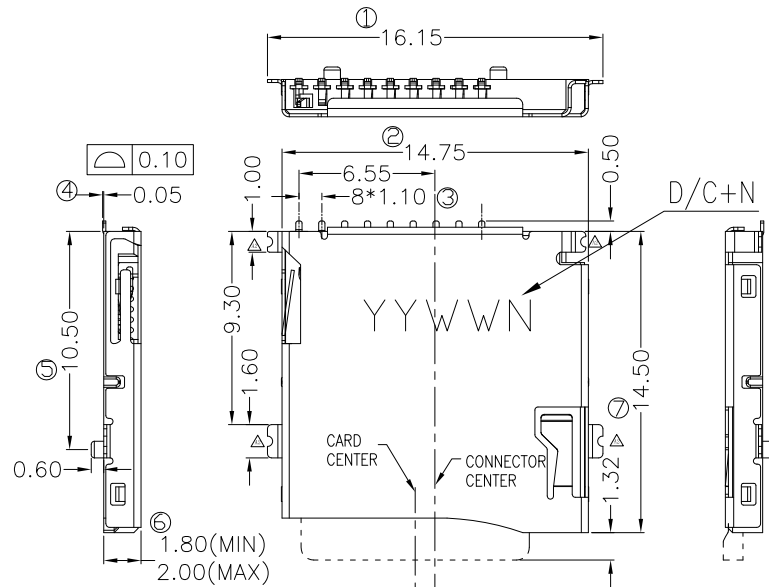


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2016/01/07	Phebe Su
A1			Change printing	2017/07/26	Phebe Su
A2			Change shell	2018/03/07	Summer Wang

RECOMMENDED P.C.B HOLE LAYOUT
COMPONENT SIDE VIEW(TOLERANCE: +/-0.05)

NOTES:

1.MATERIAL:

HOUSING: HIGH TEMPERATURE THERMOPLASTIC
UL94V_0,COLOR:LCP(BLACK).

CONTACT: COPPER ALLOYS.T=0.2

COVER: COPPER ALLOYS OR STEEL. T=0.2.

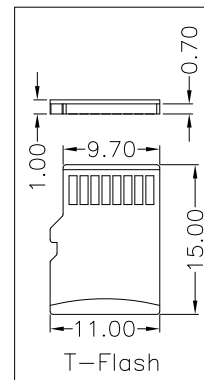
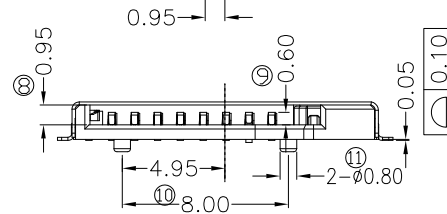
2.PLATING:

UNDERPLATE: NICKEL 100U"MIN.

CONTACT AREA: GOLD(1U") OVER NICKEL 100U" MIN.

SOLDER AREA: TIN 100U" MIN OVER NICKEL 50U" MIN.

3.MULTIMEDIA CARD COMPATIBLE



MATRIX PART NO:

MMS - 02 - 01 - 08 - 20 - 17

Matrix TF

01 : Push
02 : Non-Push

Planting
01:G/F
30:30u

Height
06:6pin
08:8pin

Series Number

PIN NO.	NAME	YTP	DESCRIPTION
1	DAT2	I/O/PP	DATE LINE(BIT2)
2	CD/DAT3	I/O/PP	CARD DETECT DATE LIN(BIT3)
3	CMD	PP	COMMAND RESPONSE
4	VDD	S	SUPPLY VOLTAGE
5	CLX	I	CLOCK
6	VSS	S	SUPPLY VOLTAGE GROUND
7	DAT0	I/O/PP	DATE LINE(BIT0)
8	DAT1	I/O/PP	DATE LINE(DIT1)

NO	VARIETY	QTY	METERIAL	REMARK
 Matrix Electronics Co.,Ltd				
TOLERANCE: X:X X:XX X:XX X:XXX ANGLE: ±3°		DESIGN BY : Summer Wang	DATE : 2018/03/07	PART NAME: TF card non push Outside welding
UNIT: mm [inch]		CHECKED BY: Vicky Hsieh	DATE : 2018/03/07	PART NO. MMS-02-01-08-20-17
SCALE:1:1 SIZE:A4		APPROVED BY1: Richard Hsieh	DATE : 2018/03/07	MOLD NO. NA
		APPROVED BY2: Richard Hsieh	DATE : 2018/03/07	DRAW NO.
				SHEET NO. 1 OF 1